|                | <spe< td=""><td>CIFICAT</td><td>ION&gt;</td><td></td></spe<> | CIFICAT                   | ION>                   |                            |
|----------------|--|---------------------------|------------------------|----------------------------|
| <b>T</b>       |  |                           |                        | DIQ-SPE-142(00)<br>25,2022 |
| То :           |  |                           |                        |                            |
|                | CUSTOM   | ER'S PRODUCT NA           | ME                     |                            |
|                |  | DDUCT NAME:<br>20B-SERIES |                        |                            |
|                |  |                           |                        |                            |
|                | NATION   |                           | CONDITIONAL CO         | DNSENT                     |
|                | APPROVED   |                           | CHECKED                |                            |
| ASDI SIGNATURE | APPROVED<br>Xianglong Li                                     | CHECKED<br>Liang Wang     | PREPARED<br>Jiayin Cai |                            |



| REV. | DATE        | DESCRIPTION | APPROVED     | CHECKED    | PREPARED   |
|------|-------------|-------------|--------------|------------|------------|
| 00   | Jul.25,2022 | New release | Xianglong Li | Liang Wang | Jiayin Cai |
|      |             |             |              |            |            |
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# **CAUTION WHEN HANDLING**

Before use the products, please read this specification.

# **CAUTION FOR SAFETY USING**

When use the products, be careful to mentioned below for safety using.

| *The product should be used with   | in 12 monthes.                      |                              |
|--|-------------------------------------|------------------------------|
| Focus on the storage conditions.   |                                     |                              |
| Solderability may become weak if   | it exceeds the period.              |                              |
| *Do not use and store the product  | •                                   |                              |
| (Salt,Acid,Alkaline).  |                                     |                              |
| *The products must be preheated  | before soldering.                   |                              |
| The operating temperature includi  | •                                   | /ithin'- <b>40 ~ +125</b> ℃. |
| *Rework by soldering iron;Please   | • •                                 |                              |
| *In case of insert P.C. Board on cl  |                                     |                              |
| *Be careful to arrange of non-mag  |                                     | ·                            |
| The error may be caused by magi  | ••                                  |                              |
| *In case handle the products, plea   | se use wrist strap for ground stat  | ic discharge on human        |
| body.  |                                     | -                            |
| The product keeps away from ma   | gnet or magnetized things.          |                              |
| *Do not use the product beyond th  | ne mentioned conditions in this sp  | ecification.                 |
| *About an application  |                                     |                              |
| The products listed on this specified  | cation sheet are intended for use   | in general electronic        |
| equipment  |                                     |                              |
| (AV equipment, telecommunicatio  |                                     |                              |
| computer equipment, personal eq  |                                     | irement equipment,           |
| industrial robots) under a normal o  | -                                   |                              |
| *The products are not designed o   |                                     |                              |
| listed below, whose performance  |                                     |                              |
| reliability, or whose failure, malfun  |                                     |                              |
| person or property. Please unders  | •                                   |                              |
| liability caused by use of the produ   |                                     | -                            |
| exceeding the range or conditions  | -                                   |                              |
| 1)Aerospace/Aviation equipment   | 6)Transportation control equip      |                              |
| 2)Military equipment   | 7)Power-generation control ec       |                              |
| 3)Seabed equipment   | which directly endanger hu          |                              |
| 4)Safety equipment   | 8)Atomic energy-related equip       |                              |
| 5)Medical equipment  | 9)Other applications that are r     |                              |
|  | considered general-purpose          |                              |
| If you intend to use the products in   | The following applications, please  | e contact our sales          |
| office.  | lectric traine chine ate ) Dublic i | formation processing         |
| Transportation equipment (cars, e  |                                     |                              |
| equipment, Electric heating appar<br>prevention equipment  | alus / burning equipment, Disaste   | r prevention/chime           |
|  | al nurness applications, you are ki | indly requested to take      |
| When using this product in generation consideration securing protection securing prote |                                     |                              |
| ensure higher safety.  |                                     | י המסגמף הויטונס, פנט., נט   |
| chourd higher salety.  |                                     |                              |
|  |                                     |                              |

ASDIQ-SPE-142(00)

| CUSTOMER         | ASDI PART No.    | CUSTOMER'S DWG NO. |
|------------------|------------------|--------------------|
| Each Corporation | AMPV4020B-SERIES |                    |

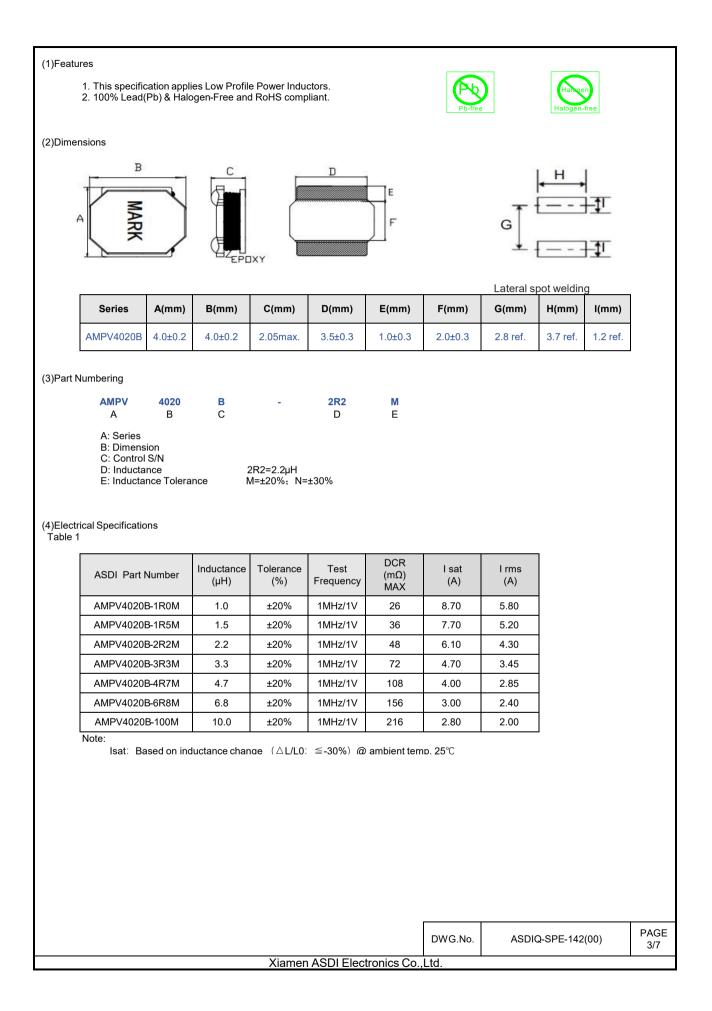
# 1.INDEX

| Listed item                 | Attachment&Tables | Page |
|-----------------------------|-------------------|------|
| 1.Features                  | Please see (1)    | 3/8  |
| 2.Dimensions                | Please see (2)    | 3/8  |
| 3.Part Numbering            | Please see (3)    | 3/8  |
| 4.Electrical Specifications | Please see (4)    | 3/8  |
| 5.Material List             | Please see (5)    | 5/8  |
| 6.Reliability Tests         | Please see (6)    | 5/8  |
| 7.Soldering                 | Please see (7)    | 7/8  |
| 8.Packaging Information     | Please see (8)    | 7/8  |
| 9.Note                      | Please see (9)    | 8/8  |

## 2.Manufacturing Location

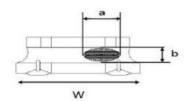
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|                | DWG.No.     | ASDIQ-SPE-142(00) | PAGE<br>2/8 |
|----------------|-------------|-------------------|-------------|
| Xiamen ASDI EI | ectronics C | o.,Ltd.           |             |



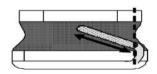
Vacant appearance tolerance Limit

Size of vacancies occurring to coating resin is specified below.



External appearance criterion for exposed wire Exposed end of the winding wire at the secondary side should be 2mm and below.

The appearance standard of the chipping size in top side, of bottom side ferrite core is following dimension



Exposed wire tolerance limit of coating resin part on product side. Size of exposed wire occurring to coating resin is specified below. 1.Width direction(dimension a): Acceptable when  $a \le 1/2W$ Nonconforming when a > w1/2W

2.Length direction(dimension b): Dimension b is not specified.3.When total area of exposed wire occurring to each sides is not greater than 50% of coating resin area, that is acceptable.

|                       | DWG.No.     | ASDIQ-SPE-142(00) | PAGE<br>4/8 |
|-----------------------|-------------|-------------------|-------------|
| Xiamen ASDI Electroni | cs Co.,Ltd. |                   |             |

## (5)Material List

| <b>A A A</b> |     |         |               |
|--------------|-----|---------|---------------|
|              | No. | Items   | Materials     |
|              | 1   | Core    | Ni-Zn ferrite |
|              | 2   | Wire    | Copper Wire   |
|              | 3   | Coating | Ероху         |
| 4            | 4   | Solder  | Lead free     |

(6)Reliability Tests

| No. | Test item                            | Performance   | Test details  |
|-----|--------------------------------------|---|---|
| 1   | Operating<br>temperature             | - 40 ~ +125℃.   | Including self-generated heat   |
| 2   | Storage<br>Temperature               | -40 ~ +85 $^\circ\! {\mathbb C}$ .<br>- 5 to 40 $^\circ\! {\mathbb C}$ for the product with taping. |   |
| 3   | Rated current                        |   |   |
| 4   | Inductance (L)                       | Within the specified tolerance  | LCR Meter: HP 4285A or equivalent, 100kHz, 1V   |
| 5   | DC Resistance                        |   | DC Ohmmeter: HIOKI3227 or equivalent  |
| 6   | Temperature<br>characteristics       | Inductance change: Within±20%   | Measurement of inductance shall be taken at<br>temperature rang within–25°C to +85°C.<br>With reference to inductance value at+20°C,change<br>rate shall be calculated.<br>Measurement of inductance shall be taken at<br>temperature rang within–40°C to +125°C.<br>With reference to inductance value at+20°C,change<br>rate shall be calculated.   |
| 7   | Resistance to flexure substrate      | No damage   | The test samples shall be soldered to the testing<br>board by the reflow.<br>As illustrated below, apply force in the direction of the<br>arrow indicating until deflection of the test board<br>reaches to 2mm.<br>reaches to 2mm.<br>Board<br>reaches to 2mm.<br>Substrate size: 100x40x1.0<br>Substrate material: glass epoxy-resin<br>Solder cream thickness: 0.15<br>1.2 1.6 1.2   |
| 8   | Adhesion of<br>Terminal<br>electrode | Shall not come off PC board.  | The test samples shall be soldered to the testing board and by the reflow.  |
| 9   | Resistance to<br>Vibration           | Inductance change: Within±10%<br>No abnormality observed in appearance.                             | The test samples shall be soldered to the test board<br>by the reflow.<br>Then it shall be submitted to below test conditions.<br>Frequency: 10-55Hz<br>Total Amplitude: 1.5mm (May not exceed acceleration<br>196m/S2 )<br>Sweeping Method:10Hz to 55Hz to 10Hz for 1min.<br>Time: 2 hours each in X,Y, and Z Direction.<br>Recovery: At least 2hrs of recovery under the<br>standard condition after the test, followed by the<br>measurement within 48hrs. |
|     |                                      |   |   |
|     |                                      |   | DWG.No. ASDIQ-SPE-142(00)   |

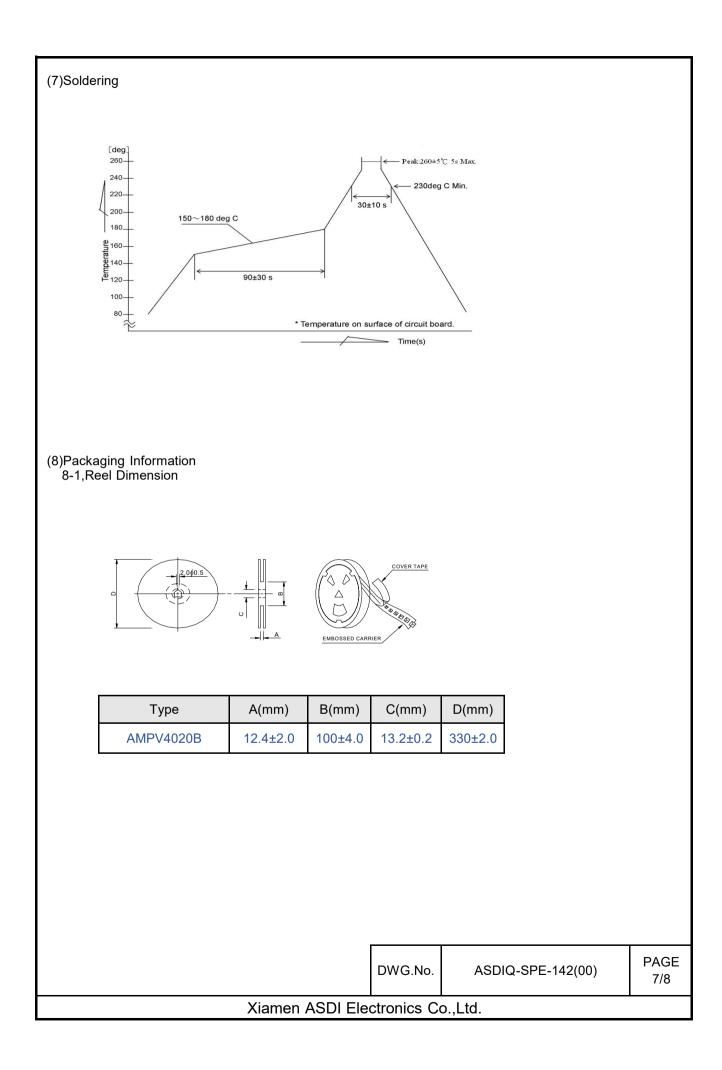
| No. | Test item                             | Performance  | Test details   |
|-----|---------------------------------------|--|--|
| 10  | Solderability                         | At least 90% of surface of terminal electrode<br>is covered by new solder. | The test samples shall be dipped in flux, and then<br>immersed in molten solder as shown in below.<br>Flux: methanol solution containing rosin 25%<br>Solder temperature: 245±5°C<br>Time: 5±1.0 sec.<br>Immersion depth: All sides of mounting terminal<br>shall be immersed.   |
| 11  | Resistance to soldering               | Inductance change:Within±10%<br>No abnormality observed in appearance.     | The test sample shall be exposed to reflow oven a<br>230±5℃ for 40 seconds, with peak temperature at<br>260±5℃ for 5 seconds,2 times.<br>Test board thickness: 1.0mm<br>Test board material: glass epoxy-resin   |
| 12  | Thermal shock                         |  | The test samples shall be soldered to the test<br>board by the reflow.<br>The test samples shall be placed at specified<br>temperature for specified time by step 1 to step 4<br>as shown below in sequence.<br>The temperature cycles shall be repeated 100<br>cycles .<br>Phase Temperature(C) Time(min.)<br>1 -40±3C - 30±3<br>2 Room Temp Within 3<br>3 85±2C - 30±3<br>4 Room Temp Within 3 |
| 13  | Damp heat life test                   | Inductance change: Within±10%  | Test Method and Remarks The test samples shall<br>be soldered to the test board by the reflow.<br>The test samples shall be placed in thermostatic<br>oven set at specified temperature and humidity as<br>shown in below.<br>Temperature: 60±2°C<br>Humidity: 90~95%RH<br>Time: 500+24/-0 hrs   |
| 14  | Loading under<br>damp heat life test  | No abnormality observed in appearance.                                     | The test samples shall be soldered to the test<br>board by the reflow.<br>The test samples shall be placed in thermostatic<br>oven set at specified temperature and humidity and<br>applied the rated current continuously as shown in<br>below.<br>Temperature: $60\pm2^{\circ}$ C<br>Humidity: 90-95%RH<br>Applied current: Rated current<br>Time: 500+24/-0 hrs                               |
| 15  | Low<br>temperature life test          |  | The test samples shall be soldered to the test<br>board by the reflow.<br>After that, the test samples shall be placed at test<br>conditions as shown in below.<br>Temperature:-40±2°C<br>Time:500+24/-0 hrs   |
| 16  | Loading at high temperature life test |  | The test samples shall be soldered to the test<br>board by the reflow.<br>Temperature: 85±2°C.<br>Applied current: Rated current<br>Time: 500+24/-0 hrs.   |

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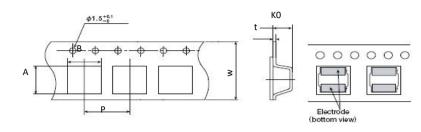
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PAGE 6/8

ASDIQ-SPE-142(00)



### 8-2, Tape Dimension



| Series    | A(mm)    | B(mm)    | Ko(mm)  | P(mm)   | W(mm)    | t(mm)    |
|-----------|----------|----------|---------|---------|----------|----------|
| AMPV4020B | 4.25±0.1 | 4.25±0.1 | 2.3±0.1 | 8.0±0.1 | 12.0±0.3 | 0.3±0.05 |

### 8-3, Packaging Quantity

| Туре      | Chip / Reel |
|-----------|-------------|
| AMPV4020B | 3000        |

### (9)Note

·Storage Conditions

To maintain the solderability of terminal electrodes: 1. ASDI products meet IPC/JEDEC J-STD-020D standard-MSL, level 1.

2. Temperature and humidity conditions: Temperature: 5 to 30deg.C, Humidity: 75% Max.

3. Recommended products should be used within 12 months form the time of delivery.

4. The packaging material should be kept where no chlorine or sulfur exists in the air.

·Transportation

1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.

2. The use of tweezers or vacuum pick up is strongly recommended for individual components.

3. Bulk handling should ensure that abrasion and mechanical shock are minimized.

|                                  | DWG.No. | ASDIQ-SPE-142(00) | PAGE<br>8/8 |
|----------------------------------|---------|-------------------|-------------|
| Xiamen ASDI Electronics Co.,Ltd. |         |                   |             |